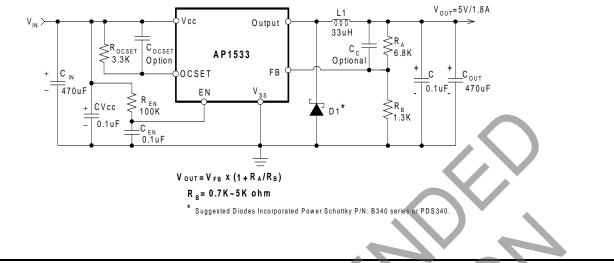


Typical Application Circuit



Pin Descriptions

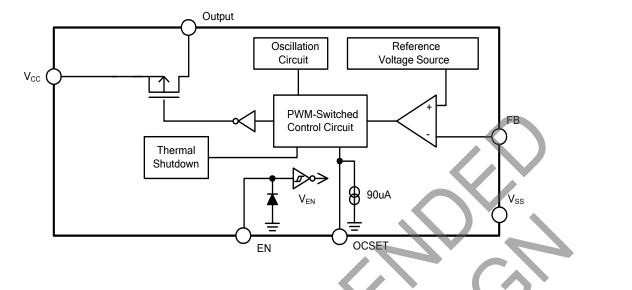
Pin Name	Pin No.	Description
FB	1	Feedback pin
EN	2	Power-off pin H: Normal operation (Step-down operation) L: Step-down operation stopped (All circuits deactivated)
OCSET	3	Add an external resistor to set max output current
Vcc	4	IC power supply pin
Output	5, 6	Switch Pin. Connect external inductor/diode here. Minimize trace area at this pin to reduce EMI
V _{SS}	7, 8	GND Pin





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Block Diagram



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	8	KV
ESD MM	Machine Model ESD Protection	500	V
Vcc	V _{CC} Pin Voltage	V _{SS} - 0.3 to V _{SS} + 24	V
Vfb	Feedback Pin Voltage	Vss - 0.3 to Vcc	V
Ven	EN Pin Voltage	Vss - 0.3 to VIN + 0.3	V
Vout	Switch Pin Voltage	Vss - 0.3 to V _{IN} + 0.3	V
PD	Power Dissipation	Internally limited	mW
TJ	Operating Junction Temperature Range	-20 to +125	°C
T _{ST}	Storage Temperature Range	-65 to +150	°C

Caution: The absolute maximum ratings are rated values exceeding which the product could suffer physical damage. These values must therefore not be exceeded under any conditions.

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
Vin	Input Voltage	4	23	V
Ιουτ	Output Current	0	1.8	А
TA	Operating Ambient Temperature	-25	+85	°C



Electrical Characteristics

Symbol	Parameter	Conditions	Min	Тур.	Max	Unit	
Vfb	Feedback Voltage	Iout = 0.1A	0.784	0.8	0.816	V	
I _{FB}	Feedback Bias Current	I _{OUT} = 0.1A	—	0.1	0.5	μA	
ISHDN	Current Consumption During Power Off	Ven = 0V	_	10		μA	
ΔVout / Vin	Line Regulation	V _{IN} = 5V~23V	—	1	2	%	
ΔVουτ / Vουτ	Load Regulation	IOUT = 0.1 to 1.8A	_	0.2	0.5	%	
fosc	Oscillation Frequency	Measure waveform at SW pin	240	300	400	KHz	
fosc1	Frequency of Current Limit or Short Circuit Protection	Measure waveform at SW pin	_	50		KHz	
VIH	EN Pin Input Voltage	Evaluate oscillation at SW pin	2.0	—	_	V	
VIL		Evaluate oscillation stop at SW pin	_	-	0.8	v	
I _{SH}	EN Pin Input Leakage Current	EN Pin High		20		μA	
I _{SL}	EN FILLIPUL LEakage Current	EN Pin Low		-10		μA	
IOCSET	OCSET Pin Bias Current	-	75	90	105	μA	
D		Vin=5V, Vfb=0V	—	110	150		
Rds(on)	Internal MOSFET RDS(ON)	VIN=12V, VFB=0V	_	80	110	mΩ	
EFFI	Efficiency	Vin=12V, Vout = 5V Iout=1.8A	E	91	_	%	
TSHDN	Thermal shutdown threshold	-	X	+150	—	°C	
THYS	Thermal shutdown hysteresis	-		+55	—	°C	
θ _{JA}	Thermal Resistance Junction-to- Ambient	SOP-8L (Note 4)		134	_	°C/W	
θJC	Thermal Resistance Junction-to-Case	SOP-8L (Note 4)	_	22	—	°C/W	

(VIN = 12V, $T_A = 25^{\circ}C$, unless otherwise specified)

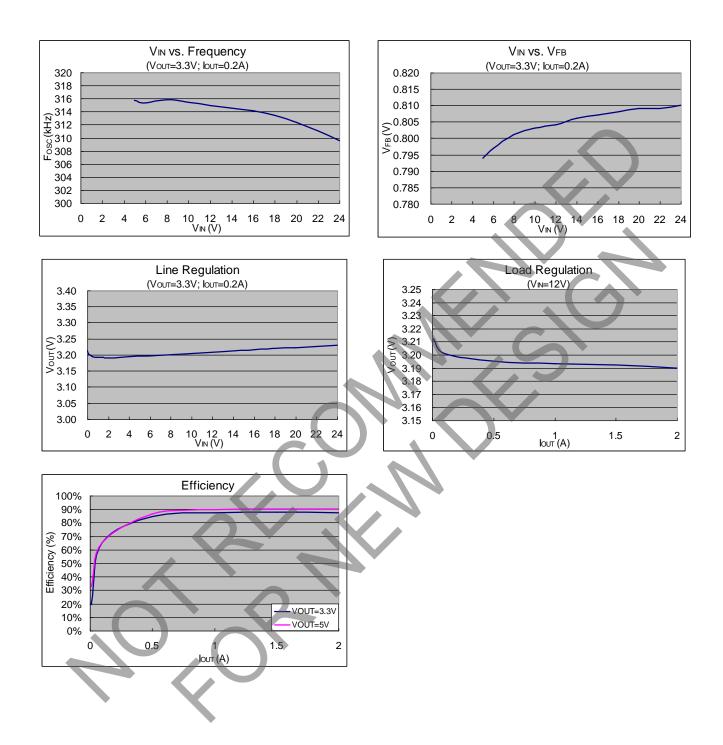
4. Test condition: Device mounted on FR-4 PCB, 2"x2", 2oz copper, minimum recommended pad layout, single side. For better thermal performance, larger copper pad for heatsink is needed. Note:





AP1533

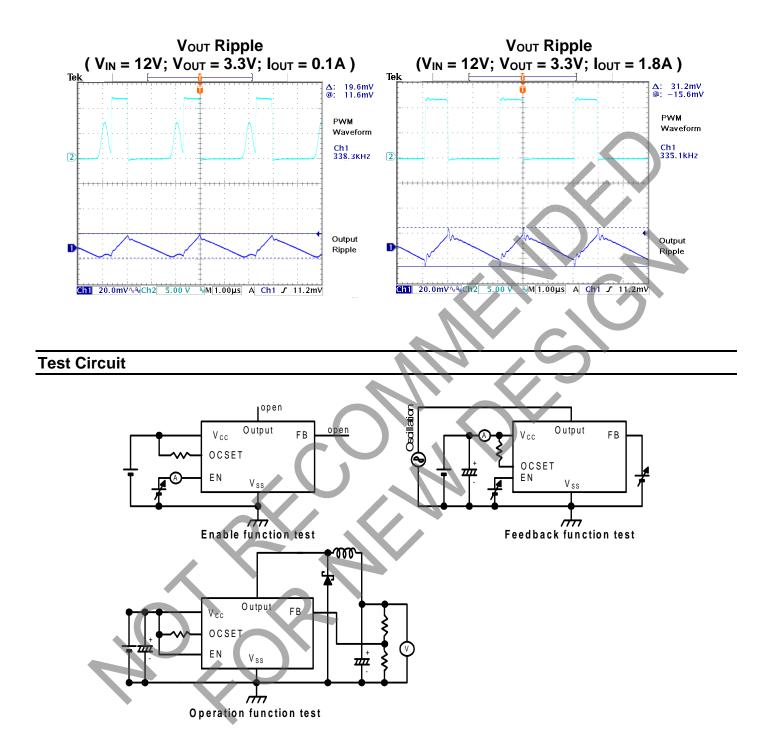
Typical Performance Characteristics





AP1533

Typical Performance Characteristics (continued)





Functional Description

PWM Control

The AP1533 is a DC/DC converter that employs pulse width modulation (PWM) scheme. Its pulse width varies in the range of 0% to 99%, based on the output current loading. The output ripple voltage caused by the PWM high frequency switching can easily be reduced through an output filter. Therefore, this converter provides a low ripple output supply over a broad range of input voltage & output current loading.

Under Voltage Lockout

The under voltage lockout circuit of the AP1533 assures that the high-side MOSFET driver remains in the off state whenever the supply voltage drops below 3.3V. Normal operation resumes once V_{CC} rises above 3.5V.

Current Limit Protection

The current limit threshold is set by external resistor R_{OCSET} connected from V_{CC} supply to OCSET pin. The internal sink current I_{OCSET} (90µA typical) across this resistor sets the voltage at OCSET pin. When the PWM voltage is less than the voltage at OCSET, an over-current condition is triggered.

The current limit threshold is given by the following equation:

$$I_{PEAK} \times R_{DS(ON)} = I_{OCSET} \times R_{OCSE}$$

$$I_{\text{PEAK}} > I_{\text{OUT}(\text{MAX})}^+$$

where,

IPEAK is the output peak current; $R_{DS (ON)}$ is the MOSFET ON resistance; fs is the PWM frequency (300KHz typical). Also, the inductor value will affect the ripple current ΔI .

The above equation is recommended for input voltage range of 5V to 18V. For input voltage lower than 5V or ambient temperature over +100°C, higher Rocset is recommended.

The recommended minimu	n Rocert value	ic cumn	arized below.
	II NOUSET VALUE	, 19 Sullill	anzeu below.

Vin (V)	Vout (V)	Rocset (Ω)	
4	0.8	3.9K	
5	3.3	3.3K	
12	5	3.3K	
18	12	3.3K	
23	12	4.7K	

The maximum ROCSET value should not exceed AP1533 maximum current output.

Inductor Selection

For most designs, the operation range with inductors is from 22µH to 33µH. The inductor value can be derived from the following equation:

$$L = \frac{V_{IN} - V_{OUT}}{fs \times \Delta I} \times \frac{V_{OUT}}{V_{IN}}$$

Where ΔI_L is inductor Ripple Current. Large value inductors lower ripple current and small value inductors result in high ripple current. Choose inductor ripple current approximately 15% of the maximum load current 1.8A, $\Delta I_L=0.27A$. The DC current rating of the inductor should be at least equal to the maximum load current plus half the ripple current to prevent core saturation (1.8A+0.135A).



Functional Description (continued)

Input Capacitor Selection

This capacitor should be located close to the IC using short leads and the voltage rating should be approximately 1.5 times the maximum input voltage. The RMS current rating requirement for the input capacitor of a buck regulator is approximately 1/2 the DC load current. A low ESR input capacitor sized for maximum RMS current must be used. A 470µF low ESR capacitor for most applications is sufficient.

Output Capacitor Selection

The output capacitor is required to filter the output voltage and provides regulator loop stability. The important capacitor parameters are the 100KHz Equivalent Series Resistance (ESR), the RMS ripples current rating, voltage rating and capacitance value. For the output capacitor, the ESR value is the most important parameter. The output ripple can be calculated from the following formula.

$$V_{RIPPLE} = \Delta I_L \times ESR$$

The bulk capacitor's ESR will determine the output ripple voltage and the initial voltage drop after a high slew-rate transient.

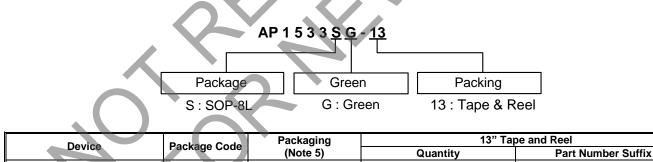
An aluminum electrolytic capacitor's ESR value is related to the capacitance and its voltage rating. In most case, higher voltage electrolytic capacitors have lower ESR values. Most of the time, capacitors with much higher voltage ratings may be needed to provide the low ESR values required for low output ripple voltage.

PCB Layout Guide

If you need low T_C & T_J or large P_D (Power Dissipation), The dual SW pins(5& 6) and V_{SS} pins(7& 8)on the SOP-8L package are internally connected to die pad, The evaluation board should be allowed for maximum copper area at output (SW) pins.

- 1. Connect FB circuits as closely as possible and keep away from inductor flux for pure VFB.
- 2. Connect input capacitor to V_{CC} and V_{SS} pin as closely as possible to get good power filter effect.
- 3. Connect R_{OCSET} to V_{CC} and OCSET pin as closely as possible.
- 4. Connect ground side of the input capacitor & Schottky & output capacitor as closely as possible and use ground plane for best performance.

Ordering Information



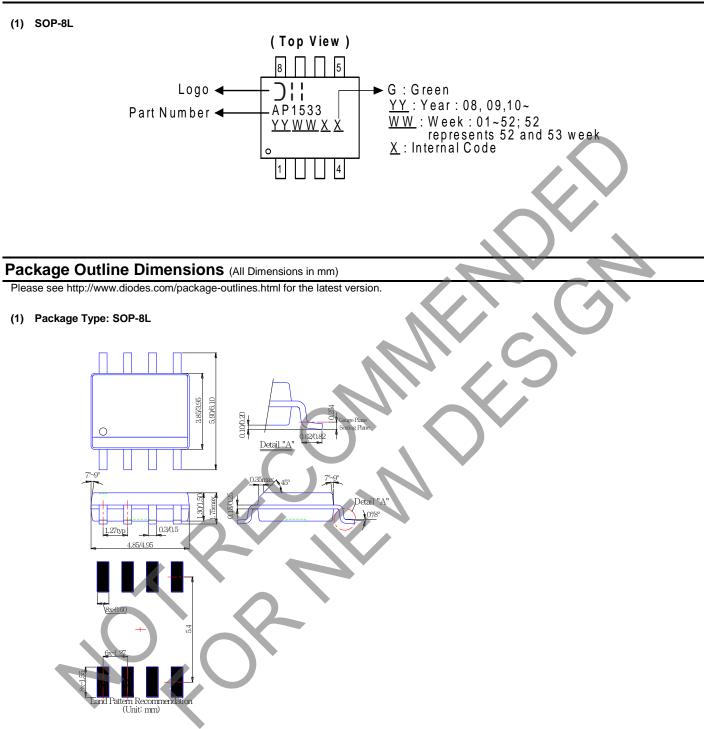
 AP1533SG-13
 S
 SOP-8L
 2500/Tape & Reel
 -13

 Note:
 5. Pad layout as shown as shown in Diodes Incorporated's package outline PDFs, which can be found on our website at http://www.diodes.com/package-outlines.html.
 -13

AP1533 Document number: DS31192 Rev. 6 - 3 Downloaded from Arrow.com.



Marking Information





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